

In the Specification:

Please amend the following paragraphs beginning on page 10, line 10 as follows:

In this example, the top layer 128 of the cloth 120, for instance, the pierce and laser respondent layer, has three bonding pads 122a associated therewith. A system of connections 132, particularly a plurality of resistors formed in parallel and/or series, run throughout the layer 128, (a schematic representation of which is illustrated in Fig. 9), and connect the traces 125 within inside the layer 128 to the bonding pads 122a. Similarly, the bottom layer 130, for instance, the delaminating respondent layer, has three bonding pads 122b associated therewith. A system of connections 134, particularly a plurality of resistors formed in parallel and/or series, run throughout the layer 130, (a graphic representation of which is illustrated in Fig. 9), and connect the traces 125 within inside the layer 130 to the bonding pads 122b.

A change in resistance within the system of connections 132, 134 indicates a break or short in the traces 125 within inside the respective layers 128, 130, e.g., caused by an attempted break-in. This change in resistance is detected as a change in voltage drop across the resistor network, which is then relayed to the corresponding bonding pads 122a, 122b of the cloth 120. The bonding pads 122a, 122b, in turn relay the change in voltage drop to the corresponding bonding pads 118 of the extension cable 112, which then transfers the message through wires 126 and interconnections 124 to the cryptographic processor card 102. Thereafter, the cryptographic processor card 102 may take the appropriate precautions to prevent the information from being divulged, such as erasing the stored key codes for encrypting and decrypting the secured information.

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